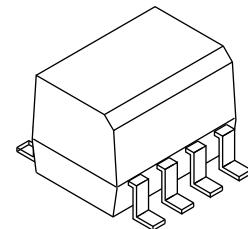


## DESCRIPTION

The MOCD213-M consist of two gallium arsenide infrared emitting diodes optically coupled to two monolithic silicon phototransistor detectors, in a surface mountable, small outline plastic package. It is ideally suited for high density applications and eliminates the need for through-the-board mounting.

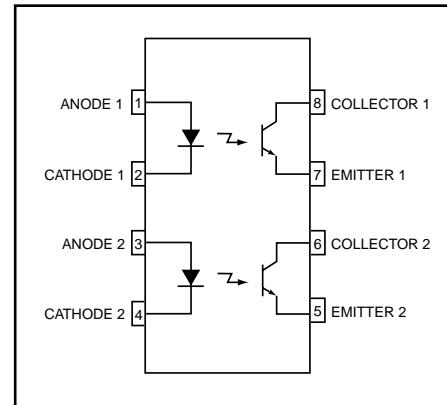


## FEATURES

- U.L. Recognized (File #E90700, Volume 2)
- VDE Recognized (File #136616) (add option "V" for VDE approval, i.e. MOCD213V-M)
- Dual Channel Coupler
- Convenient Plastic SOIC-8 Surface Mountable Package Style
- Minimum Current Transfer Ratio 100% with Input Current of 10 mA
- Minimum  $V_{(BR)}\text{CEO}$  of 70 Volts Guaranteed
- Standard SOIC-8 Footprint, with 0.050" Lead Spacing
- Compatible with Dual Wave, Vapor Phase and IR Reflow Soldering
- High Input-Output Isolation of 2500 V<sub>AC(rms)</sub> Guaranteed

## APPLICATIONS

- Feedback control circuits
- Interfacing and coupling systems of different potentials and impedances
- General purpose switching circuits
- Monitor and detection circuits



## ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ Unless otherwise specified)

Rating	Symbol	Value	Unit
<b>EMITTER</b>			
Forward Current - Continuous	$I_F$	60	mA
Forward Current - Peak ( $PW = 100 \mu\text{s}, 120 \text{ pps}$ )	$I_F(\text{pk})$	1.0	A
Reverse Voltage	$V_R$	6.0	V
LED Power Dissipation @ $T_A = 25^\circ\text{C}$	$P_D$	90	mW
Derate above 25°C		0.8	mW/°C
<b>DETECTOR</b>			
Collector-Emitter Voltage	$V_{\text{CEO}}$	70	V
Collector-Base Voltage	$V_{\text{CBO}}$	70	V
Emitter-Collector Voltage	$V_{\text{ECO}}$	7.0	V
Collector Current-Continuous	$I_C$	150	mA
Detector Power Dissipation @ $T_A = 25^\circ\text{C}$	$P_D$	150	mW
Derate above 25°C		1.76	mW/°C
<b>TOTAL DEVICE</b>			
Input-Output Isolation Voltage (1,2,3) ( $f = 60 \text{ Hz}, 1 \text{ min. Duration}$ )	$V_{\text{ISO}}$	2500	V <sub>AC(rms)</sub>
Total Device Power Dissipation @ $T_A = 25^\circ\text{C}$	$P_D$	250	mW
Derate above 25°C		2.94	mW/°C
Ambient Operating Temperature Range	$T_A$	-40 to +100	°C
Storage Temperature Range	$T_{\text{stg}}$	-40 to +150	°C
Lead Soldering Temperature (1/16" from case, 10 sec. duration)	$T_L$	260	°C

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)

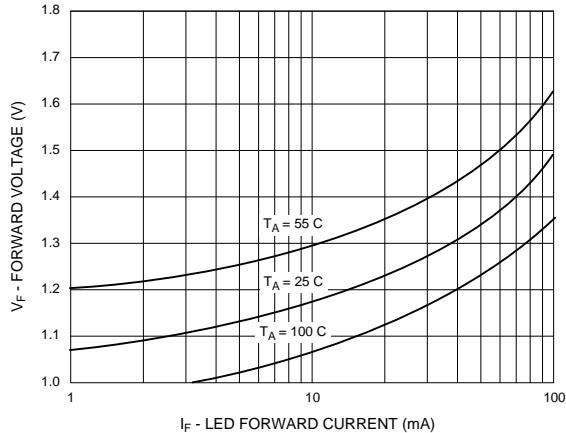
Parameter	Test Conditions	Symbol	Min	Typ**	Max	Unit
<b>EMITTER</b>						
Input Forward Voltage	$I_F = 30 \text{ mA}$	$V_F$	—	1.25	1.55	V
Reverse Leakage Current	$V_R = 6.0 \text{ V}$	$I_R$	—	0.001	100	$\mu\text{A}$
Capacitance		C	—	18	—	pF
<b>DETECTOR</b>						
Collector-Emitter Dark Current	$V_{CE} = 10 \text{ V}, T_A = 25^\circ\text{C}$	$I_{CEO1}$	—	1.0	50	nA
	$V_{CE} = 10 \text{ V}, T_A = 100^\circ\text{C}$	$I_{CEO2}$	—	1.0	—	$\mu\text{A}$
Collector-Emitter Breakdown Voltage	$I_C = 100 \mu\text{A}$	$BV_{CEO}$	70	120	—	V
Emitter-Collector Breakdown Voltage	$I_E = 100 \mu\text{A}$	$BV_{ECO}$	7.0	7.8	—	V
Collector-Emitter Capacitance	$f = 1.0 \text{ MHz}, V_{CE} = 0 \text{ V}$	$C_{CE}$	—	7.0	—	pF
<b>COUPLED</b>						
Output Collector Current <sup>(4)</sup>	$I_F = 10 \text{ mA}, V_{CE} = 5 \text{ V}$	CTR	100	—	—	%
Collector-Emitter Saturation Voltage	$I_C = 2.0 \text{ mA}, I_F = 10 \text{ mA}$	$V_{CE} (\text{sat})$	—	0.15	0.4	V
Turn-On Time	$I_C = 2.0 \text{ mA}, V_{CC} = 10 \text{ V}, R_L = 100 \Omega$ (Fig.6)	$t_{on}$	—	3.0	—	$\mu\text{s}$
Turn-Off Time	$I_C = 2.0 \text{ mA}, V_{CC} = 10 \text{ V}, R_L = 100 \Omega$ (Fig.6)	$t_{off}$	—	2.8	—	$\mu\text{s}$
Rise Time	$I_C = 2.0 \text{ mA}, V_{CC} = 10 \text{ V}, R_L = 100 \Omega$ (Fig.6)	$t_r$	—	1.6	—	$\mu\text{s}$
Fall Time	$I_C = 2.0 \text{ mA}, V_{CC} = 10 \text{ V}, R_L = 100 \Omega$ (Fig.6)	$t_f$	—	2.2	—	$\mu\text{s}$
Isolation Surge Voltage <sup>(1,2,3)</sup>	$f = 60 \text{ Hz}, t = 1 \text{ min.}$	$V_{ISO}$	2500	—	—	V <sub>AC(rms)</sub>
Isolation Resistance <sup>(2)</sup>	$V_{I-O} = 500 \text{ V}$	$R_{ISO}$	$10^{11}$	—	—	$\Omega$
Isolation Capacitance <sup>(2)</sup>	$V_{I-O} = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{ISO}$	—	0.2	—	pF

\*\* Typical values at  $T_A = 25^\circ\text{C}$

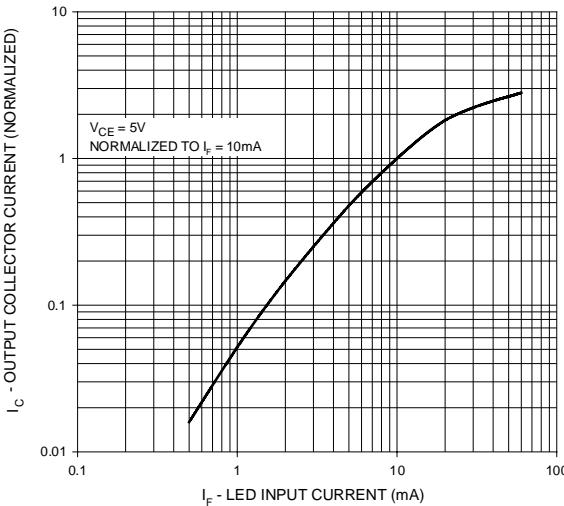
**NOTE:**

1. Input-Output Isolation Voltage,  $V_{ISO}$ , is an internal device dielectric breakdown rating.
2. For this test, Pins 1, 2, 3 and 4 are common and Pins 5, 6, 7 and 8 are common.
3.  $V_{ISO}$  rating of 2500 V<sub>AC(rms)</sub> for  $t = 1 \text{ min.}$  is equivalent to a rating of 3,000 V<sub>AC(rms)</sub> for  $t = 1 \text{ sec.}$
4. Current Transfer Ratio (CTR) =  $I_C/I_F \times 100\%$ .

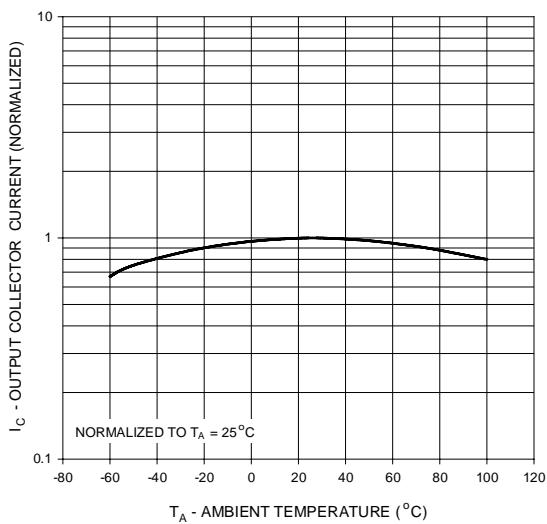
**Fig. 1 LED Forward Voltage vs. Forward Current**



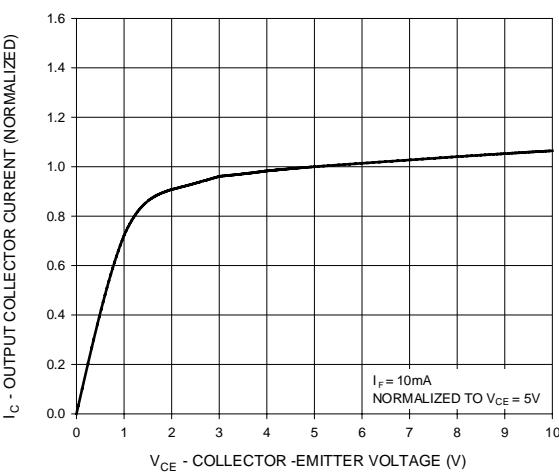
**Fig. 2 Output Current vs. Input Current**



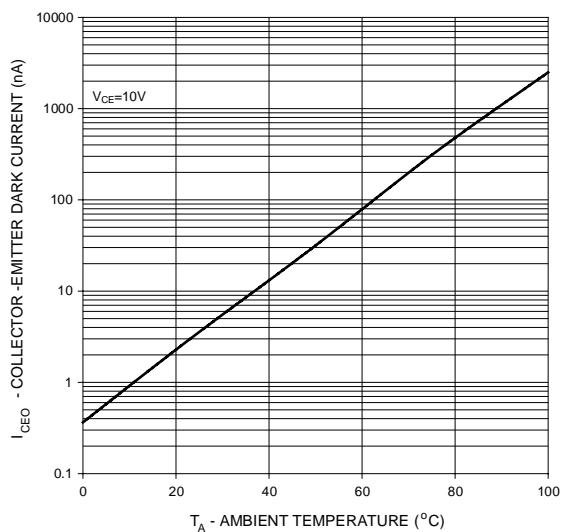
**Fig. 3 Output Current vs. Ambient Temperature**

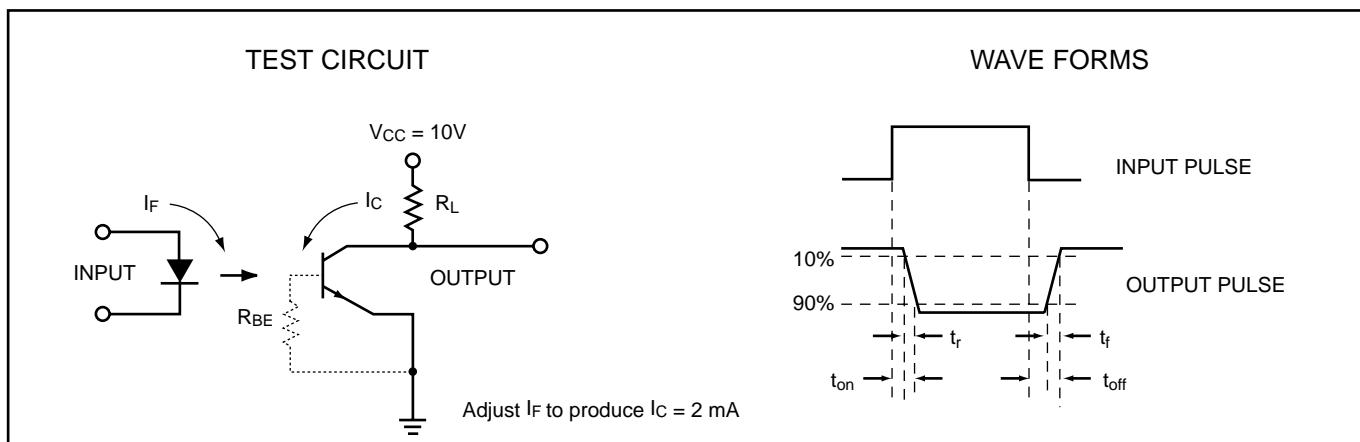


**Fig. 4 Output Current vs. Collector - Emitter Voltage**



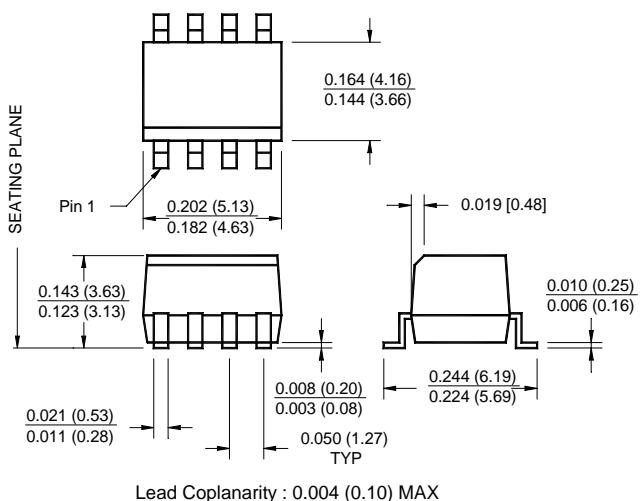
**Fig. 5 Dark Current vs. Ambient Temperature**



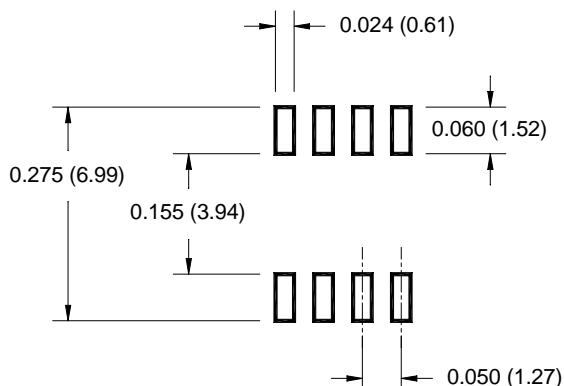


**Figure 6. Switching Time Test Circuit and Waveforms**

**Package Dimensions (Surface Mount)**



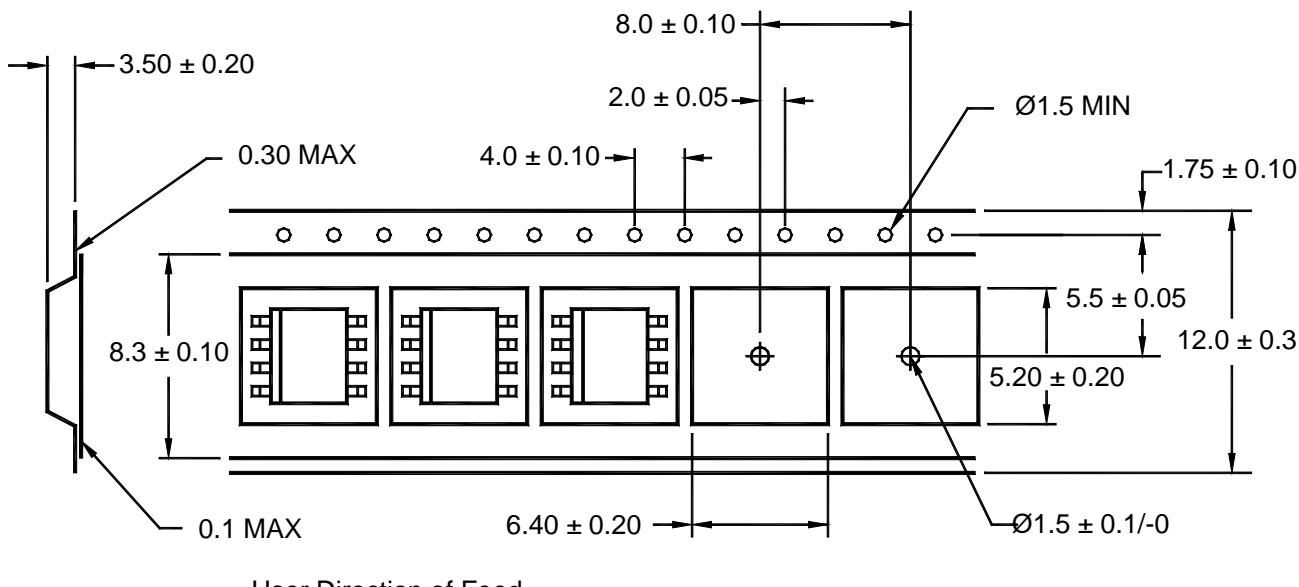
**8 - Pin Small Outline**



**ORDERING INFORMATION**

Option	Order Entry Identifier	Description
V	V	VDE 0884
R1	R1	Tape and reel (500 units per reel)
R1V	R1V	VDE 0884, Tape and reel (500 units per reel)
R2	R2	Tape and reel (2500 units per reel)
R2V	R2V	VDE 0884, Tape and reel (2500 units per reel)

**QT Carrier Tape Specifications ("D" Taping Orientation)**





# DUAL CHANNEL PHOTOTRANSISTOR SMALL OUTLINE SURFACE MOUNT OPTOCOUPERS

**MOCD213-M**

## **DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

## **LIFE SUPPORT POLICY**

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.